

**AMENDMENTS TO THE SPECIFICATION:**

Please replace the paragraph beginning at page 2, line 16, with the following amended paragraph.

D1  
In a head assembly 10 shown in FIG. 1A, a head slider 20 is mounted on a gimbal part 12 which is provided on a tip end of a suspension 11. As shown in FIG. 1B, a head IC chip 30 is mounted face-down in a head IC chip mounting part 15 which is located at a central part of the suspension 11. The head IC chip 30 is a ~~bear~~ bare chip, such that a main chip body 31 which is made of silicon is exposed.

Please replace the paragraph beginning at page 18, line 15, with the following amended paragraph.

D2  
Furthermore, the peripheral side surfaces 85a of the under-filling 85 are also covered by the poly (p-xylylene) layer 110. Thus, foreign particles are also prevented from being generated from the peripheral side surfaces 85a of the under-filling 85. Therefore, compared to a case where only the ~~bear~~ bare head IC chip 80 is covered by the poly (p-xylylene) layer 110, the disk unit 100 has a considerably improved reliability in that the head crash is unlikely to occur due to the foreign particles which are prevented from being generated.

Please replace the paragraph beginning at page 20, line 23, with the following amended paragraph.

D3  
Particularly because the upper surface 81b and the entirety of the side surfaces 81c of the main chip body 81 are covered by the poly (p-xylylene) layer 110, the silicon particles are prevented from separating from a ~~bear~~ bare head IC chip 80A, so as to prevent generation of the foreign particles or powder.